

TD6MF610

Surface Mount Bridge Rectifier
Reverse Voltage - 1000 V
Forward Current - 6 A

Features

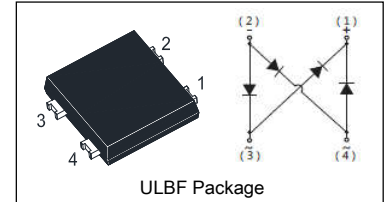
- Fast reverse recovery time
- Designed for surface mount application

Mechanical Data

- Case: ULBF
- Terminals: Solderable per MIL-STD-750, Method 2026

Pinning

PIN	Description
1	Output Anode (+)
2	Output Cathode (-)
3	Input pin (-)
4	Input pin (-)



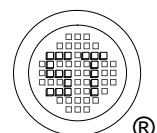
Absolute Maximum Ratings ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Value	Unit
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	1000	V
Maximum RMS Voltage	V_{RMS}	700	V
Maximum DC Blocking Voltage	V_{DC}	1000	V
Average Rectified Forward Current at $T_C = 100^\circ\text{C}$	$I_{F(AV)}$	6	A
Peak Forward Surge Current 8.3 ms Single half sine-wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	200	A
Rating for Fusing	$I^2 t$	166	A^2S
Typical Thermal Resistance from Junction to Lead ¹⁾	$R_{\theta JL}$	14	$^\circ\text{C/W}$
Typical Thermal Resistance from Junction to Case ¹⁾	$R_{\theta JC}$	6	$^\circ\text{C/W}$
Typical Thermal Resistance from Junction to Ambient ¹⁾	$R_{\theta JA}$	60	$^\circ\text{C/W}$
Operating Junction and Storage Temperature Range	T_j, T_{stg}	- 55 to + 150	$^\circ\text{C}$

¹⁾ Mounted on glass epoxy PC board with $4 \times 1.5'' \times 1.5''$ (3.81×3.81 cm) copper pad.

Characteristics at $T_a = 25^\circ\text{C}$

Parameter	Symbol	Typ.	Max.	Unit
Forward Voltage at $I_F = 6$ A	V_F	-	1.1	V
Reverse Current at Rated DC Blocking Voltage $T_j = 25^\circ\text{C}$ $T_j = 125^\circ\text{C}$	I_R	- -	5 200	μA
Reverse Recovery Time at $I_F = 0.5$ A, $I_R = 1$ A, $I_{rr} = 0.25$ A	t_{rr}	-	500	ns
Junction Capacitance at $V_R = 4$ V DC, $f = 1$ MHz	C_j	100	-	pF



Electrical Characteristics Curves

Fig.1 Average Rectified Output Current Derating Curve

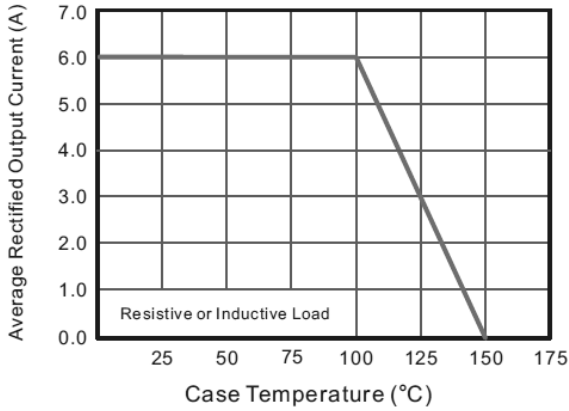


Fig.2 Typical Reverse Characteristics

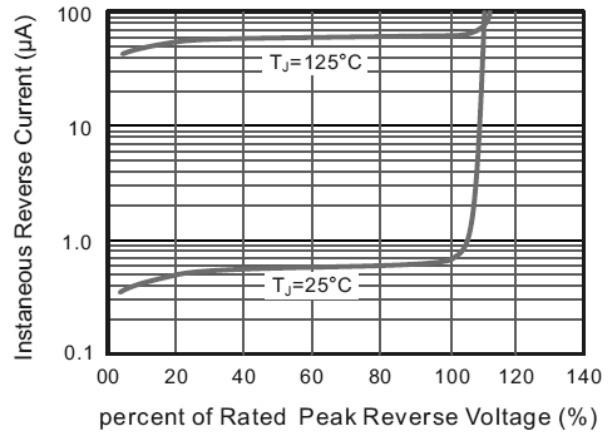


Fig.3 Typical Instantaneous Forward Characteristics

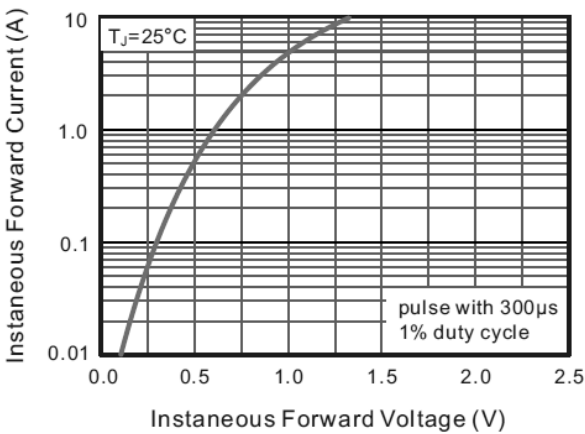


Fig.4 Typical Junction Capacitance

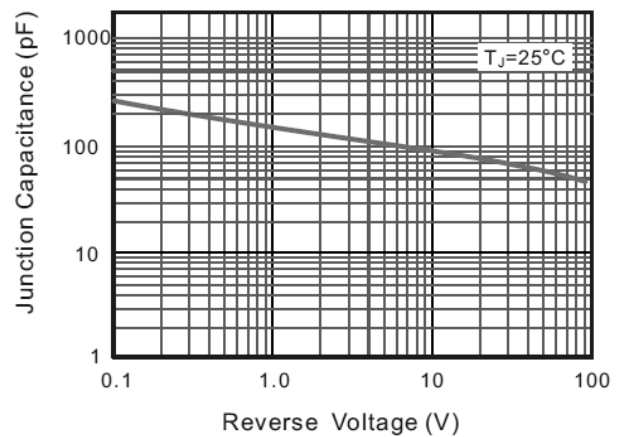


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

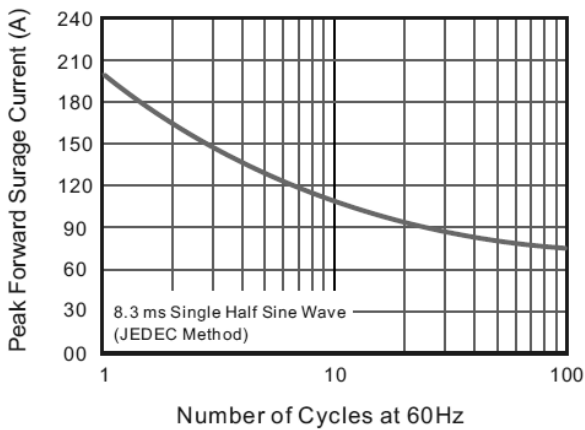
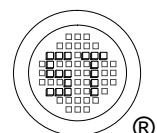
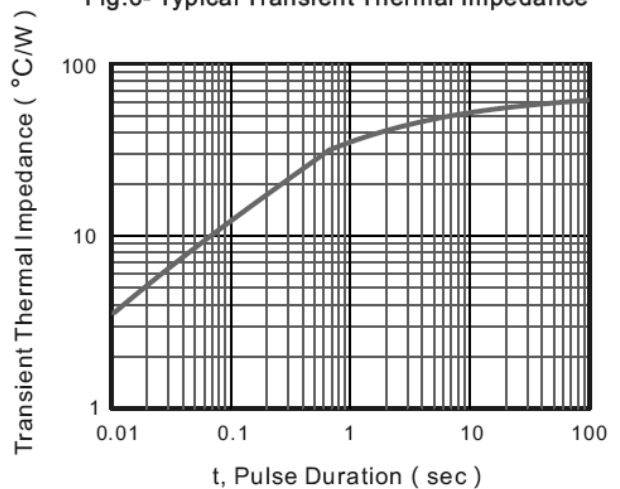


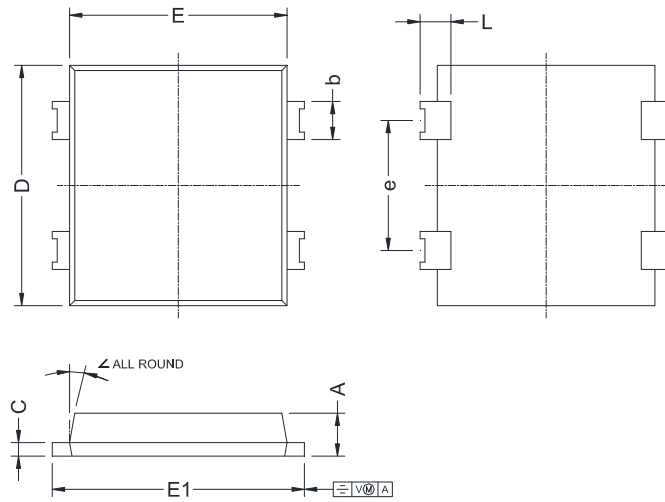
Fig.6- Typical Transient Thermal Impedance



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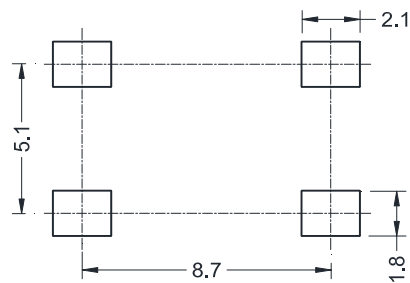
Package Outline Dimensions (Units: mm)

ULBF



UNIT	A	C	D	E	E1	L	e	b	\angle
mm	1.75	0.55	9.8	8.8	10.2	1.25	5.3	1.55	10°
	1.35	0.25	9.4	8.4	9.8	0.85	4.9	1.25	

Recommended Soldering Footprint



Marking information

- " ULBR610 " = Part No.
- " YYWW " = Date Code Marking
 - " Y " = Year (ex: 19 = 2019)
 - " W " = Week (ex: 09 = the 9th week of the year)

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